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## FACSIMILE MESSAGE — PLEASE DELIVER PROMPTLY

FOR: NAME Examiner J. Lee  
 COMPANY Art Unit 2501  
 FAX NUMBER 703-308-7724  
 CONFIRMATION PHONE NUMBER \_\_\_\_\_  
 VERBAL COMMUNICATION REQUESTED:  YES  NO  
 FROM: NAME S. Maebius RETURN TO \_\_\_\_\_  
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## MESSAGE:

I hereby certify that the enclosed paper  
 is being transmitted by facsimile to the PTO  
 on March 13, 1997.

Stephen B. Maebius  
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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney Docket No. 50169/105/ENPO

In re patent application of

Wallace T.Y. TANG

Group Art Unit: 2501

Serial No. 08/401,229

Examiner: J. Lee

Filed: March 9, 1995

For: IN-SITU REAL-TIME MONITORING TECHNIQUE AND APPARATUS  
FOR ENDPOINT DETECTION OF THIN FILMS DURING  
CHEMICAL/MECHANICAL POLISHING PLANARIZATIONSUPPLEMENTAL AMENDMENTAssistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

Further to the Amendment filed on December 9, 1996, please amend the above-identified application as follows:

IN THE CLAIMS

Please add the following claims:

37-76. An apparatus for chemical mechanical polishing of a wafer, comprising

(a) a rotatable polishing platen with an overlying polishing pad wetted with an abrasive slurry;

(b) a rotatable chuck for holding the wafer against the polishing pad, the wafer comprising a semiconductor substrate underlying an oxide layer; and

(c) and endpoint detector, comprising

(c1) a laser interferometer capable of generating a laser beam directed towards the wafer and detecting light reflected from the wafer, and

(c2) a hole formed through the platen and polishing pad allowing the laser beam to reflect off a section of the

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